

Precision Milling/Polishing System



X-Prep[®]
Precision Milling/Polishing



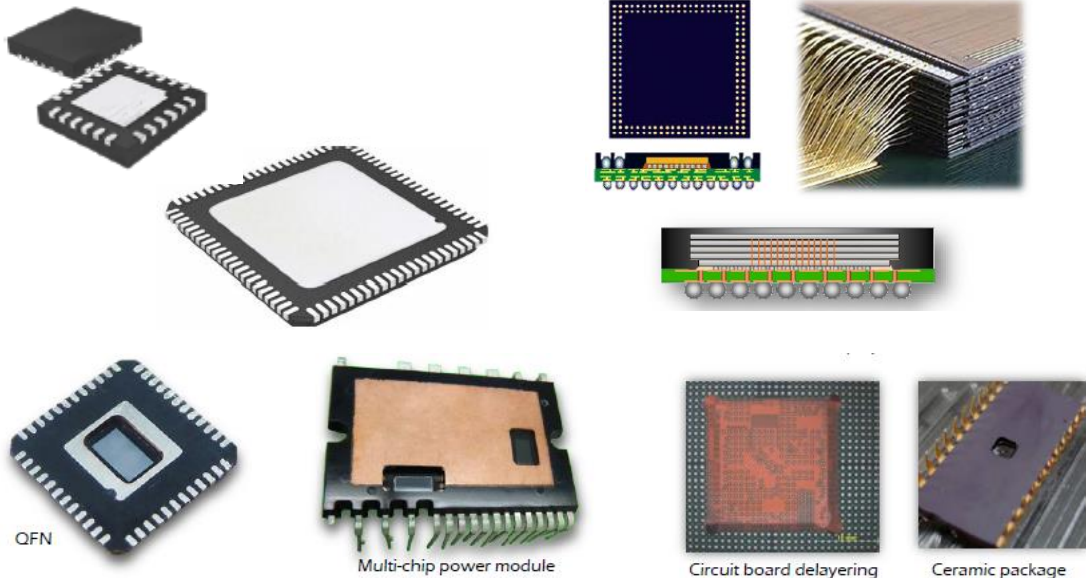
X-Prep[®] Vision[™]

제품의 상세문의는
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경기도 성남시 중원구 둔촌대로 474, 507호
(상대원동 선택시티 1차)
TEL. 031-777-1277 / FAX. 031-777-1288

Applications by X-Prep

Support Electrical and Physical failure analysis



3D TSV – Stacked Die

- Flip-chip – GPU
- NAND/Flash memory
- SoC, PoP AND SiC – mobile processors
- Hybrid Super SoC`s
- WL/CSP – Wafer and chip-scale package
- 2.5D Devices – FPGAK

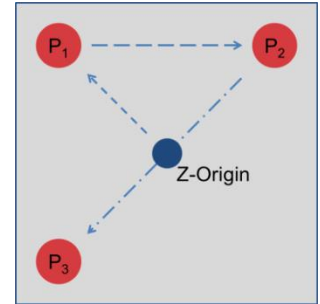
Lead Frame

- Thin small outline package
- Shrink small outline package
- Small outline IC
- Dual inline package

Leadless Quad

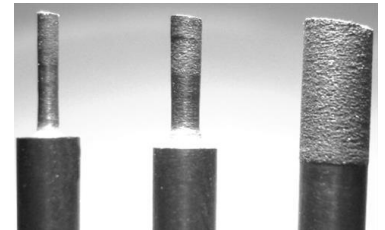
- Plastic leaded chip carrier
- Quad flat no-lead
- Quad flat package

Automatic Sample Leveling



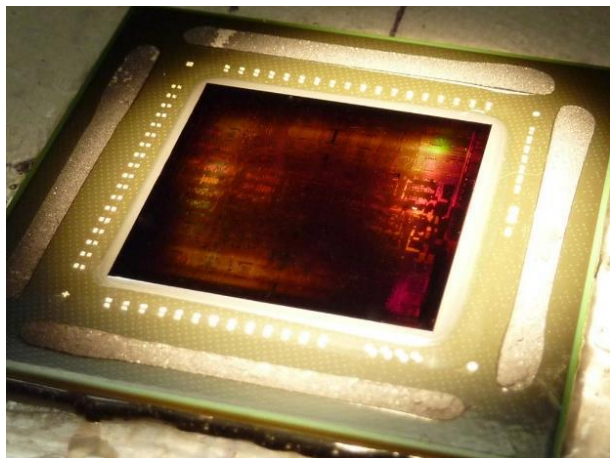
- Manual / Custom Tilt Table Control
- 0.5~75 μm Leveling Tolerance

Tools Application Guide

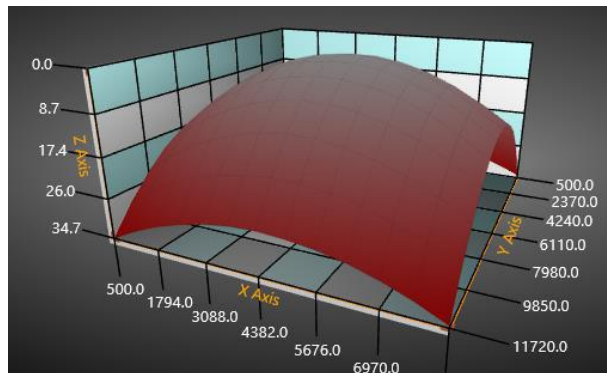


- End Mills : Copper, Aluminum, Gold, Solder, PCB
- Plated Diamond : Plastic, Composite materials, Glass, Ceramic
- Bonded Diamond : Mold compound, Si wafer
- Diamond Grinding Discs : Rapid grinding of Silicon
- Polishing Discs : Diamond paste, Slurries for Polishing

Flip-Chip Deprocessing

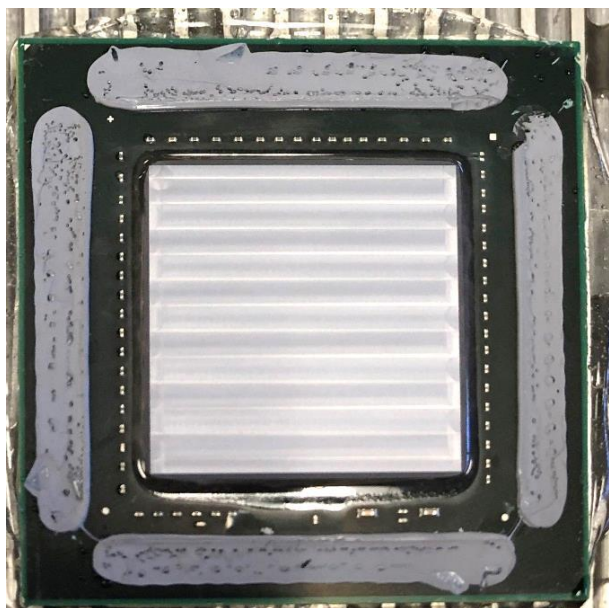


Sample

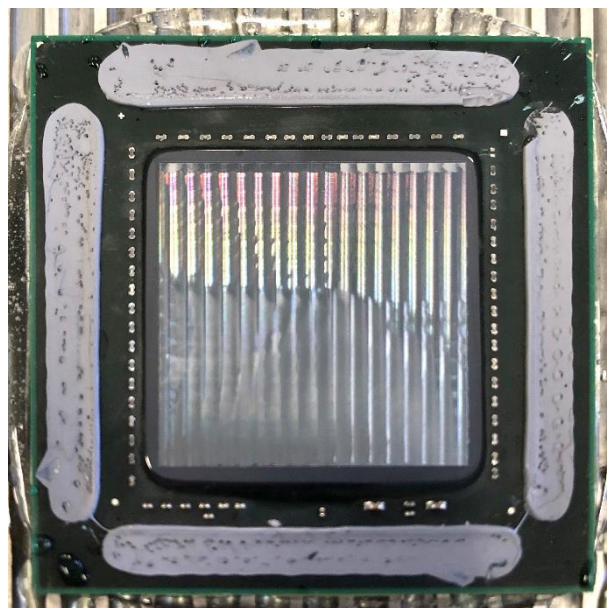


Sample Profile
by Vision

Result

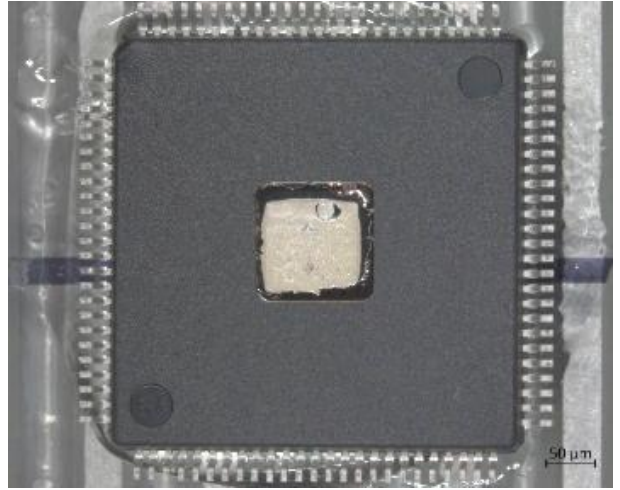
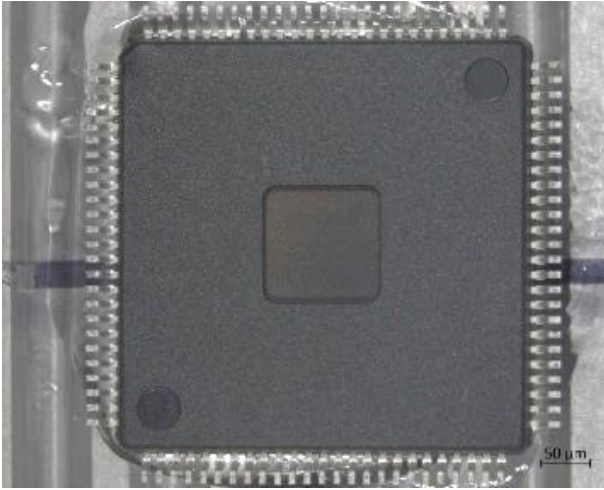


After coarse grinding

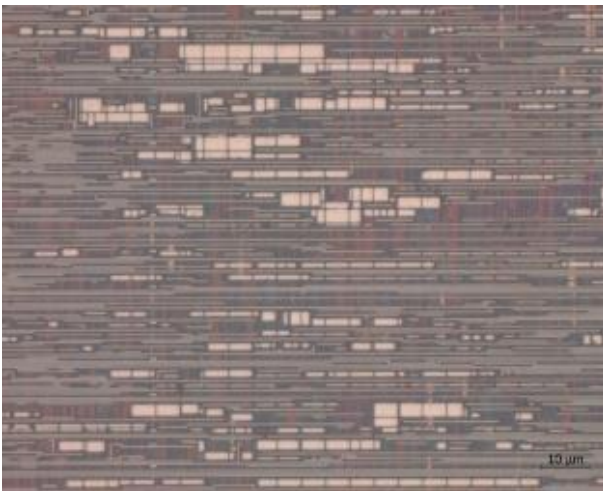


After restoring
contour/uniformity - FMB

Molded Device Deprocessing



Parallel Delayering



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